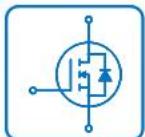




ESD



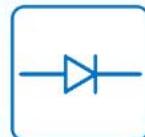
TVS



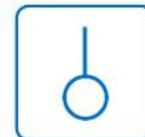
MOS



LDO



Diode



Sensor



DC-DC

## Product Specification

▶ Domestic Part Number	IPD068N10N3G
▶ Overseas Part Number	IPD068N10N3G
▶ Equivalent Part Number	IPD068N10N3G



EV is the abbreviation of name EVVO

## N-Ch 100V Fast Switching MOSFETs

### Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Fast Switching Speed
- Green Device Available

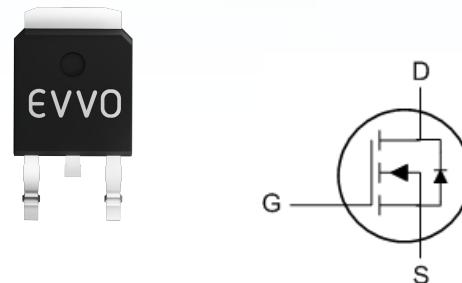
### Product Summary

BVDSS	RDS(on)	ID
100V	8.5mΩ	73A

### Applications

- High Frequency Switching and Synchronous Rectification.
- DC/DC Converter.

### TO252 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current <sup>1</sup>	73	A
I <sub>D</sub> @T <sub>C</sub> =70°C	Continuous Drain Current <sup>1</sup>	46	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	290	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	61	mJ
I <sub>AS</sub>	Avalanche Current	35	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	108	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t≤10s)	---	25	°C/W
	Thermal Resistance Junction-Ambient <sup>1</sup>	---	55	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	1.15	°C/W

**N-Ch 100V Fast Switching MOSFETs**
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

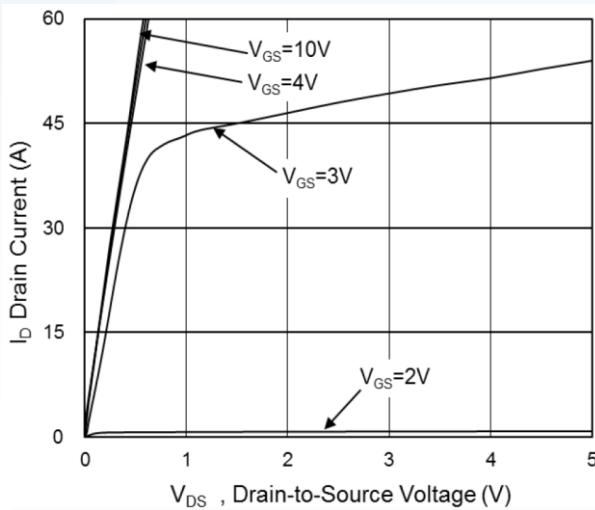
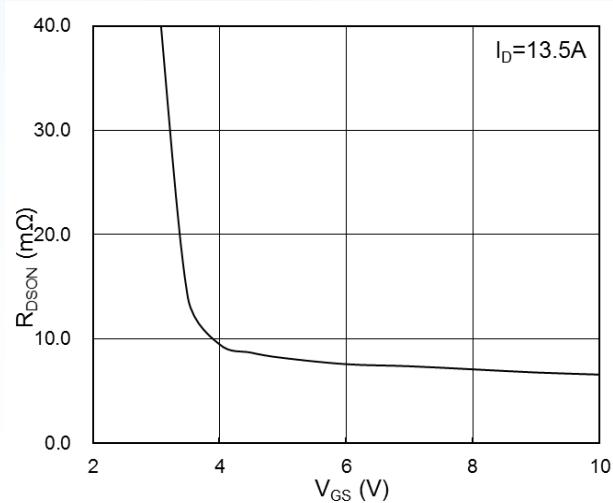
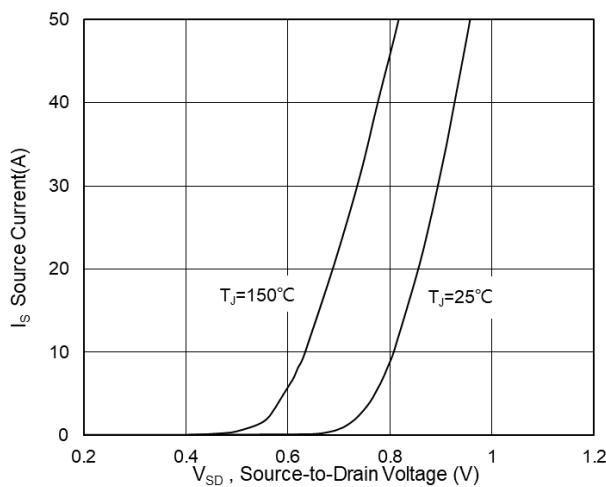
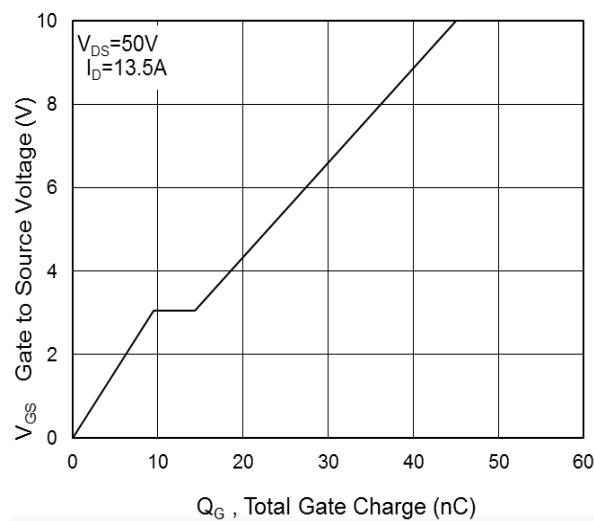
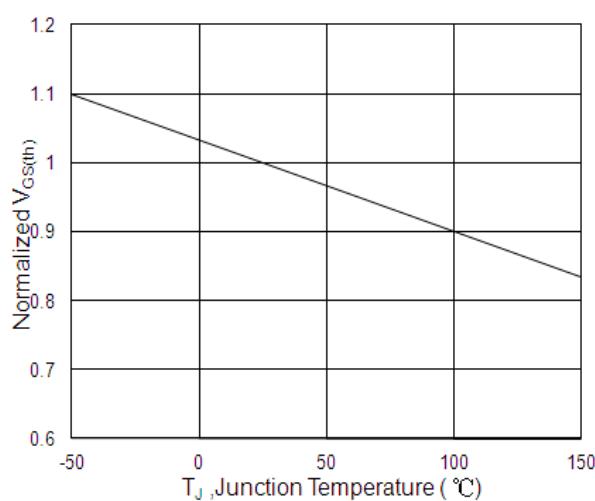
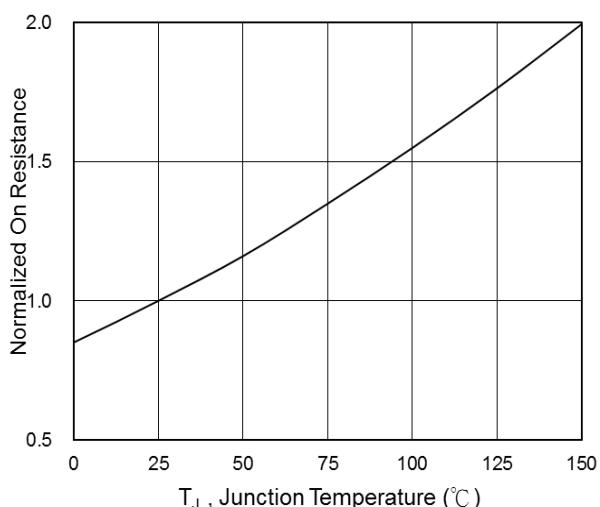
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=13.5\text{A}$	---	6.6	8.5	$\text{m}\Omega$
	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=4.5\text{V}$ , $I_D=11.5\text{A}$	---	8.7	11	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.2	---	2.3	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=20\text{A}$	---	85	---	S
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=13.5\text{A}$	---	45	---	$\text{nC}$
$Q_g$	Total Gate Charge (4.5V)		---	19.3	---	
$Q_{\text{gs}}$	Gate-Source Charge		---	9.5	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	4.8	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3\Omega$ , $I_D=13.5\text{A}$	---	10	---	$\text{ns}$
$T_r$	Rise Time		---	6.5	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	45	---	
$T_f$	Fall Time		---	7.5	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3320	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	605	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	20	---	

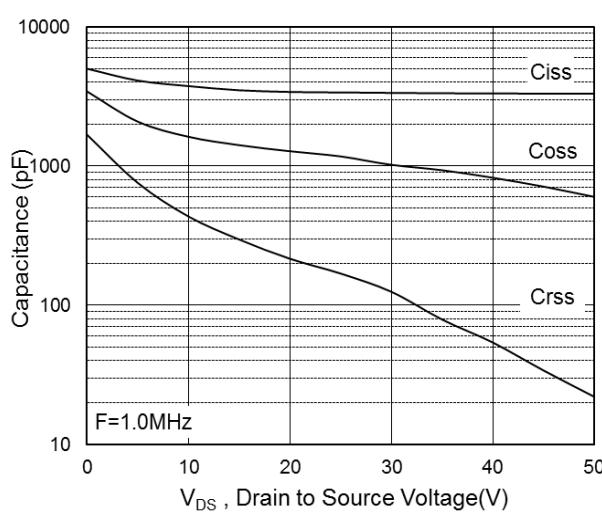
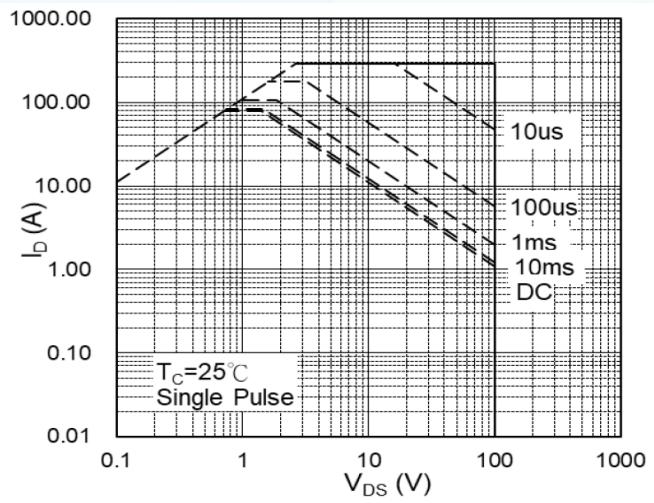
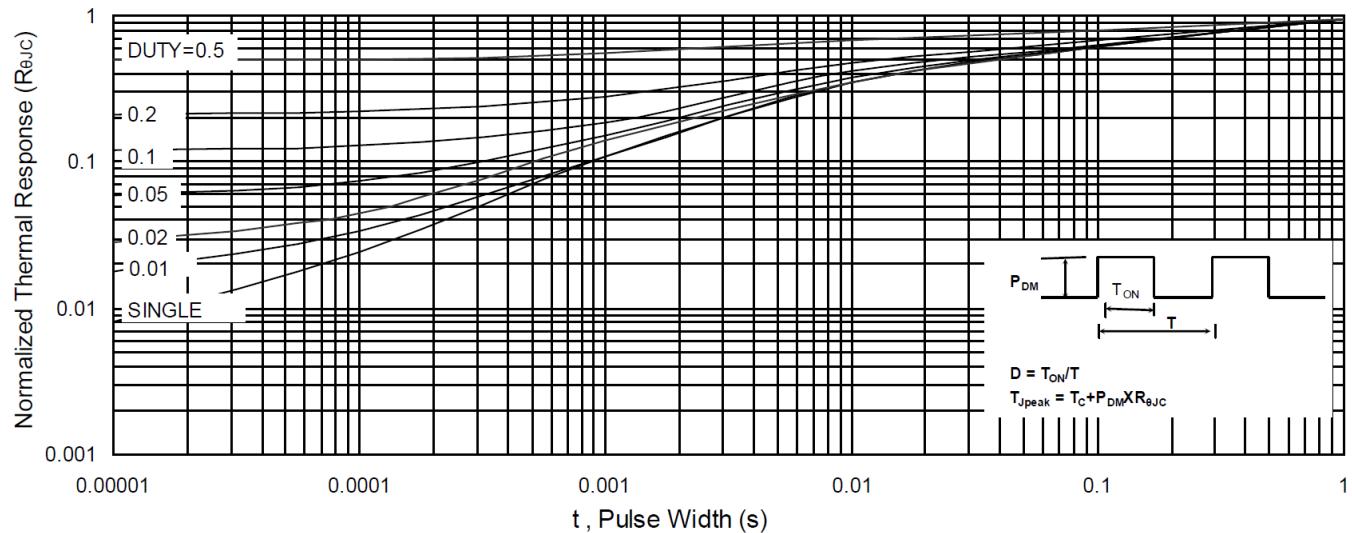
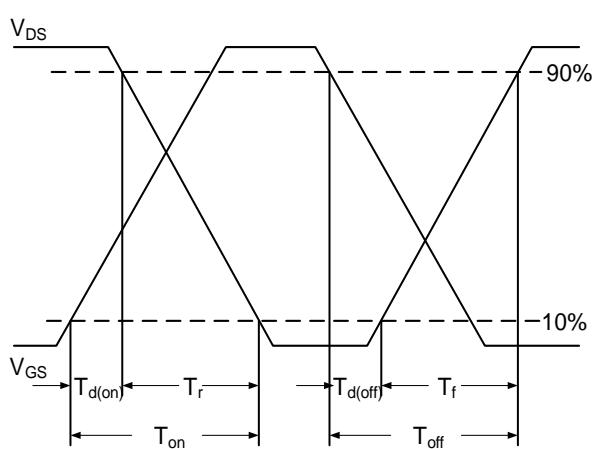
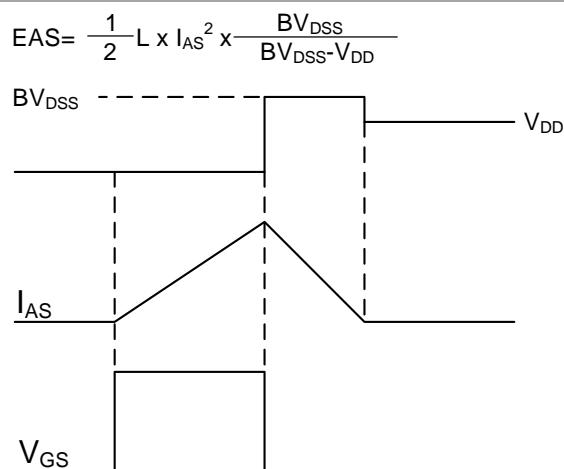
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	48	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.1	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=13.5\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	33	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	150	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.3\text{mH}$ , $I_{\text{AS}}=35\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

**N-Ch 100V Fast Switching MOSFETs**
**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.3 Source Drain Forward Characteristics**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**

**N-Ch 100V Fast Switching MOSFETs**
**Fig.7 Capacitance****Fig.8 Safe Operating Area****Fig.9 Normalized Maximum Transient Thermal Impedance****Fig.10 Switching Time Waveform****Fig.11 Unclamped Inductive Waveform**

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